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SCAS584M-NOVEMBER 1996-REVISED MARCH 2005

## FEATURES

- Bidirectional Voltage Translator
- 4.5 V to 5.5 V on A Port and 2.7 V to 5.5 V on B Port
- Control Inputs V<sub>IH</sub>/V<sub>IL</sub> Levels Are Referenced to V<sub>CCA</sub> Voltage
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

DB, DW, NS, OR PW PACKAGE (TOP VIEW)							
V <sub>CCA</sub> DIR A1 A2 A3 A4 A5 A6 A7 A8 GND GND	1 2 3 4 5 6 7 8 9 10 11 12	24 23 22 21 20 19 18 17 16 15 14 13	V <sub>CCB</sub> NC OE B1 B2 B3 B4 B5 B6 B7 B8 GND				
NC - No	internal	conr	nection				

# **DESCRIPTION/ORDERING INFORMATION**

This 8-bit (octal) noninverting bus transceiver uses two separate power-supply rails. The A port,  $V_{CCA}$ , is dedicated to accepting a 5-V supply level, and the configurable B port, which is designed to track  $V_{CCB}$ , accepts voltages from 3 V to 5 V. This allows for translation from a 3.3-V to a 5-V environment and vice versa.

The SN74LVCC4245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so the buses effectively are isolated. The control circuitry (DIR,  $\overline{OE}$ ) is powered by V<sub>CCA</sub>.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PAC	KAGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C		Tube of 25	SN74LVCC4245ADW	LVCC4245A	
	SOIC – DW	Reel of 2000	SN74LVCC4245ADWR		
	SOP – NS Reel of 2000		SN74LVCC4245ANSR	LVCC4245A	
	SSOP - DB	Reel of 2000	SN74LVCC4245ADBR	LG245A	
		Tube of 60	SN74LVCC4245APW		
	TSSOP - PW	Reel of 2000 SN74LVCC4245APWR		LG245A	
		Reel of 250	SN74LVCC4245APWT	10	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

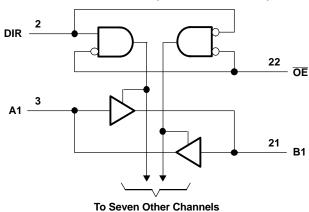
#### FUNCTION TABLE (EACH TRANSCEIVER)

1	INP	UTS	OPERATION
	OE	DIR	OPERATION
	L	L	B data to A bus
	L	н	A data to B bus
	Н	Х	Isolation

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas

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#### LOGIC DIAGRAM (POSITIVE LOGIC)

# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V <sub>CCA</sub> V <sub>CCB</sub>	Supply voltage range		-0.5	6	V	
		I/O ports (A port)	-0.5	$V_{CCA}$ + 0.5		
VI	Input voltage range <sup>(2)</sup>	I/O ports (B port)	-0.5	$V_{CCB} + 0.5$	V	
		Except I/O ports	-0.5	V <sub>CCA</sub> + 0.5		
V <sub>O</sub> Output voltage range <sup>(2)</sup>	Output voltage range <sup>(2)</sup>	A port	-0.5	V <sub>CCA</sub> + 0.5	V	
		B port	-0.5	V <sub>CCB</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA	
I <sub>O</sub>	Continuous output current			±50	mA	
	Continuous current through $V_{CCA}$ , $V_{CCB}$ , or $C$	GND		±100	mA	
		DB package		63		
0	Decline we the second imposing data as $\binom{3}{3}$	DW package		46		
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	NS package		65	°C/W	
		PW package		88		
T <sub>stg</sub>	Storage temperature range		-65	150	°C	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) This value is limited to 6 V maximum.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

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# Recommended Operating Conditions<sup>(1)</sup>

		V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	NOM	MAX	UNIT
V <sub>CCA</sub>	Supply voltage			4.5	5	5.5	V
V <sub>CCB</sub>	Supply voltage			2.7	3.3	5.5	V
		4.5 V	2.7 V	2			
V <sub>IHA</sub>	High-level input voltage	4.3 V	3.6 V	2			V
		5.5 V	5.5 V	2			
		4.5 V	2.7 V	2			
V <sub>IHB</sub>	High-level input voltage	4.3 V	3.6 V	2			V
		5.5 V	5.5 V	3.85			
		4.5 V	2.7 V			0.8	
V <sub>ILA</sub> Lo	Low-level input voltage	4.3 V	3.6 V			0.8	V
		5.5 V	5.5 V			0.8	
V <sub>ILB</sub> Lo	Low-level input voltage	4.5 V	2.7 V			0.8	V
		4.5 V	3.6 V			0.8	
		5.5 V	5.5 V			1.65	
	High-level input voltage (control pins) (referenced to $V_{CCA}$ )	4.5 V	2.7 V	2			V
V <sub>IH</sub>			3.6 V	2			
		5.5 V	5.5 V	2			
	Low-level input voltage (control pins) (referenced to $V_{CCA}$ )	4.5 V	2.7 V			0.8	V
V <sub>IL</sub>			3.6 V			0.8	
		5.5 V	5.5 V			0.8	
V <sub>IA</sub>	Input voltage			0		V <sub>CCA</sub>	V
V <sub>IB</sub>	Input voltage			0		V <sub>CCB</sub>	V
V <sub>OA</sub>	Output voltage			0		V <sub>CCA</sub>	V
V <sub>OB</sub>	Output voltage			0		V <sub>CCB</sub>	V
I <sub>OHA</sub>	High-level output current	4.5 V	3 V			-24	mA
I <sub>OHB</sub>	High-level output current	4.5 V	2.7 V to 4.5 V			-24	mA
I <sub>OLA</sub>	Low-level output current	4.5 V	3 V			24	mA
I <sub>OLB</sub>	Low-level output current	4.5 V	2.7 V to 4.5 V			24	mA
T <sub>A</sub>	Operating free-air temperature			-40		85	°C

(1) All unused inputs of the device must be held at the associated V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP	MAX	UNIT
V <sub>OHA</sub>		I <sub>OH</sub> = -100 μA	4.5 V	3 V	4.4	4.49		V
		$I_{OH} = -24 \text{ mA}$	4.5 V	3 V	3.76	4.25		V
		I <sub>OH</sub> = -100 μA	4.5 V	3 V	2.9	2.99		
		1. 12 m/	4.5 V	2.7 V	2.2	2.5		
\ <i>\</i>		$I_{OH} = -12 \text{ mA}$	4.5 V	3 V	2.46	2.85		V
V <sub>OHB</sub>				2.7 V	2.1	2.3		v
		$I_{OH} = -24 \text{ mA}$	4.5 V	3 V	2.25	2.65		
				4.5 V	3.76	4.25		
		I <sub>OL</sub> = 100 μA	4.5 V	3 V			0.1	V
V <sub>OLA</sub>		I <sub>OL</sub> = 24 mA	4.5 V	3 V		0.21	0.44	v
		I <sub>OL</sub> = 100 μA	4.5 V	3 V			0.1	
		I <sub>OL</sub> = 12 mA	4.5 V	2.7 V		0.11	0.44	
V <sub>OLB</sub>				2.7 V		0.22	0.5	V
		I <sub>OL</sub> = 24 mA	4.5 V	3 V		0.21	0.44	
				4.5 V		0.18	0.44	
L Control incuto	Control inputs	V - V or GND	5.5 V	3.6 V		±0.1	±1	μA
I <sub>I</sub>	Control Inputs	$V_{I} = V_{CCA} \text{ or } GND$	5.5 V	5.5 V		±0.1	±1	μA
I <sub>OZ</sub> <sup>(1)</sup>	A or B ports	$V_{O} = V_{CCA/B} \text{ or } GND, \qquad V_{I} = V_{IL} \text{ or } V_{IH}$	5.5 V	3.6 V		±0.5	±5	μΑ
		$A_n = V_{CC} \text{ or } GND$	5.5 V	Open		8	80	
I <sub>CCA</sub>	B to A	$I_O$ (A port) = 0, $B_n = V_{CCB}$ or GND	5.5 V	3.6 V		8	80	μΑ
		$O(A poin) = 0,$ $D_n = V_{CCB} O(B ND)$	5.5 V	5.5 V		8	80	
	A to B	$A_n = V_{CCA}$ or GND, $I_O$ (B port) = 0	5.5 V	3.6 V		5	50	^
I <sub>CCB</sub>	AIUB	$A_n = V_{CCA} \text{ or } GND, \qquad I_O (B \text{ port}) = 0$	5.5 V	5.5 V		8	80	μA
	A port	$V_{I} = V_{CCA} - 2.1$ V, Other inputs at $V_{CCA}$ or GND, OE at GND and DIR at $V_{CCA}$	5.5 V	5.5 V		1.35	1.5	
$\Delta I_{CCA}^{(2)}$	ŌĒ	$V_I = V_{CCA} - 2.1$ V, Other inputs at $V_{CCA}$ or GND, DIR at $V_{CCA}$ or GND	5.5 V	5.5 V		1	1.5	mA
	DIR	$V_{I} = V_{CCA} - 2.1$ V, Other inputs at $V_{CCA}$ or GND, $\overline{OE}$ at $V_{CCA}$ or GND	5.5 V	3.6 V		1	1.5	
$\Delta I_{CCB}^{(2)}$	B port	$V_{I} = V_{CCB} - 0.6$ V, Other inputs at $V_{CCB}$ or GND, OE at GND and DIR at GND	5.5 V	3.6 V		0.35	0.5	mA
C <sub>i</sub>	Control inputs	$V_{I} = V_{CCA}$ or GND	Open	Open		5		pF
C <sub>io</sub>	A or B ports	$V_{O} = V_{CCA/B}$ or GND	5 V	3.3 V		11		pF

 For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.
This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or the associated V<sub>CC</sub>.



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### **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1 through Figure 4)

PARAMETER	FROM	TO (OUTPUT)			$V_{CCA}$ = 5 V $\pm$ 0.5 V, $V_{CCB}$ = 2.7 V to 3.6 V		UNIT	
	(INPUT)	(001201)	MIN	MAX	MIN	MAX		
t <sub>PHL</sub>	Α	В	1	7.1	1	7	20	
t <sub>PLH</sub>	A	D	1	6	1	7	ns	
t <sub>PHL</sub>	в	А	1	6.8	1	6.2	ns	
t <sub>PLH</sub>	D	A	1	6.1	1	5.3	115	
t <sub>PZL</sub>	OE	٨	1	9	1	9	ns	
t <sub>PZH</sub>	UE	A	1	8.3	1	8		
t <sub>PZL</sub>	OE	В	1	8.2	1	10	20	
t <sub>PZH</sub>	UE	D	1	8.1	1	10.2	ns	
t <sub>PLZ</sub>	OE	А	1	4.7	1	5.2	ns	
t <sub>PHZ</sub>	UL	~	1	4.9	1	5.2	115	
t <sub>PLZ</sub>	OE	В	1	5.4	1	5.4	20	
t <sub>PHZ</sub>	UE	D	1	6.3	1	7.4	ns	

## **Operating Characteristics**

 $V_{CCA} = 5 \text{ V}, V_{CCB} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$ 

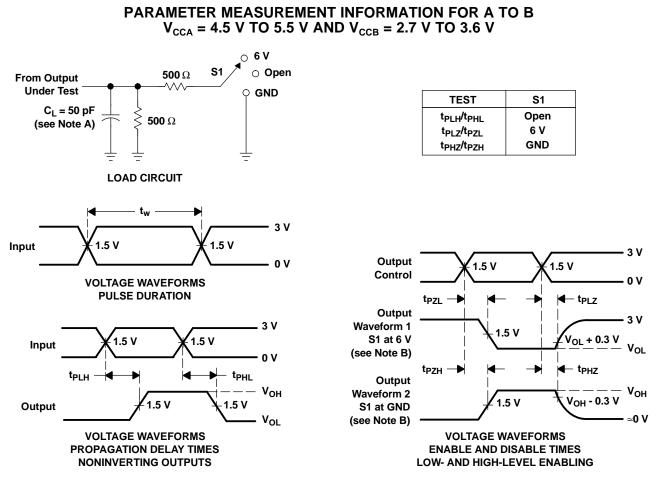
PARAMETER			TEST C	ONDITIONS	TYP	UNIT
~		Outputs enabled	<b>C O</b>	f = 10 MHz	20	
C <sub>pd</sub> Power dissipation capacitance per transceiver	Power dissipation capacitance per transceiver	Outputs disabled	$C_{L} = 0,$		6.5	pF

### Power-Up Considerations<sup>(1)</sup>

TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. Take these precautions to guard against such power-up problems:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device ( $V_{CCA}$  for all four of these devices).
- 3. Tie  $\overline{OE}$  to V<sub>CCA</sub> with a pullup resistor so that it ramps with V<sub>CCA</sub>.
- Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with V<sub>CCA</sub>. Otherwise, keep DIR low.
- (1) Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.

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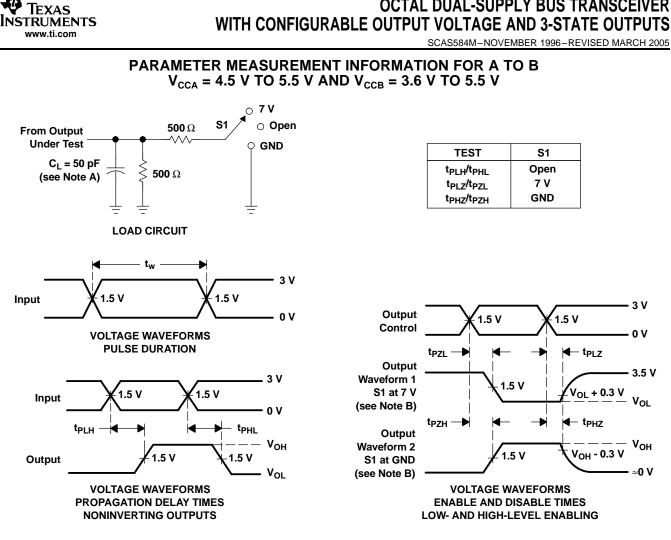
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NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

#### Figure 1. Load Circuit and Voltage Waveforms



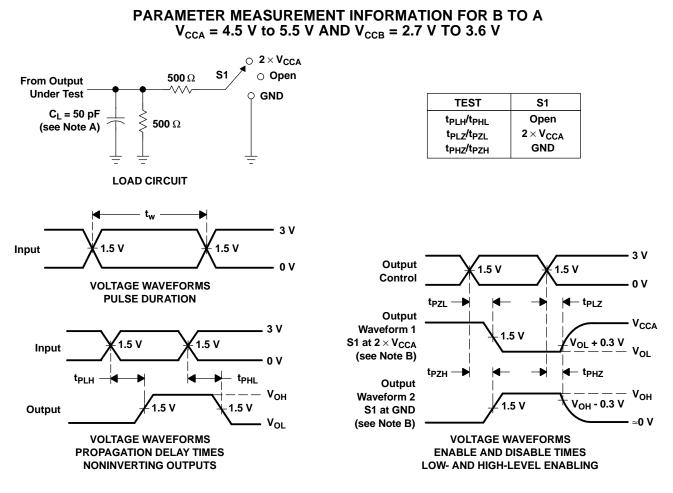
- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. All parameters and waveforms are not applicable to all devices.

#### Figure 2. Load Circuit and Voltage Waveforms

SN74LVCC4245A

**OCTAL DUAL-SUPPLY BUS TRANSCEIVER** 





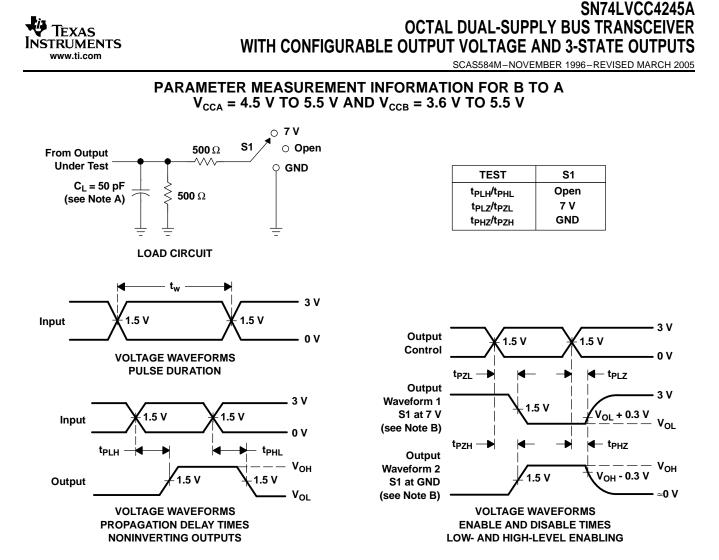
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NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns. t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

#### Figure 3. Load Circuit and Voltage Waveforms



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

#### Figure 4. Load Circuit and Voltage Waveforms



# PACKAGE OPTION ADDENDUM

9-Aug-2005

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVCC4245ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74LVCC4245ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245APWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245APWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI
SN74LVCC4245APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245APWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245APWT	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCC4245APWTE4	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is



# PACKAGE OPTION ADDENDUM

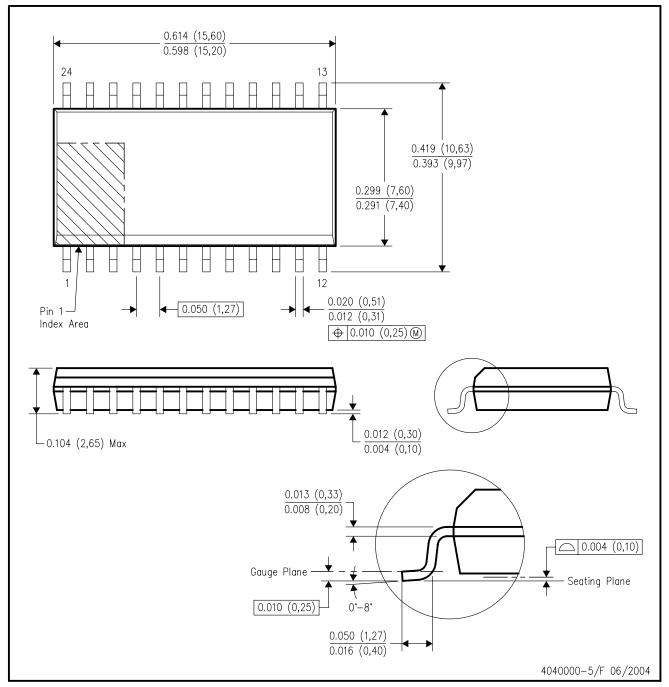
9-Aug-2005

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DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



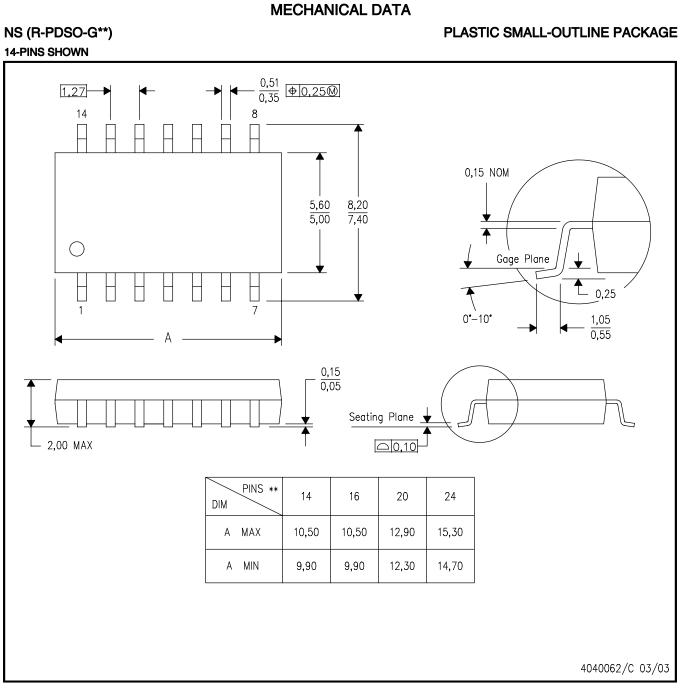
NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

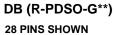
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

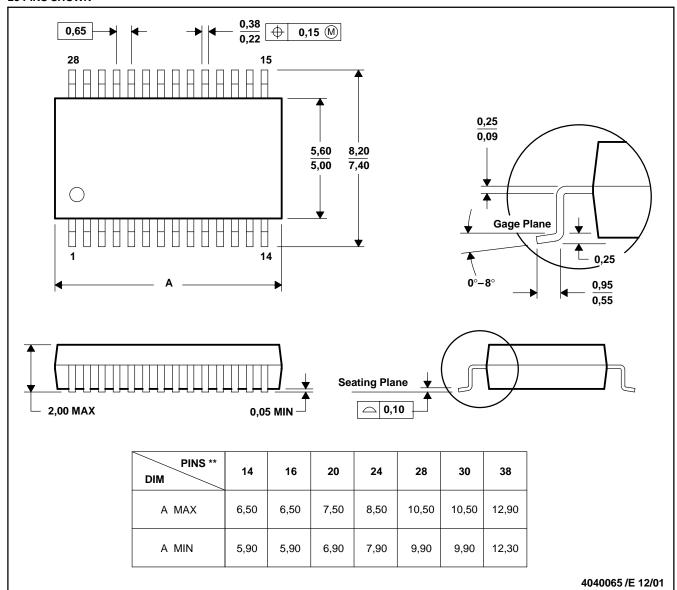


# **MECHANICAL DATA**

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150



# **MECHANICAL DATA**

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

#### PLASTIC SMALL-OUTLINE PACKAGE





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



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